

4V Drive Nch+Pch MOSFET

SP8M10FRA

●Structure

Silicon N-channel / P-channel MOSFET

●Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (SOP8).

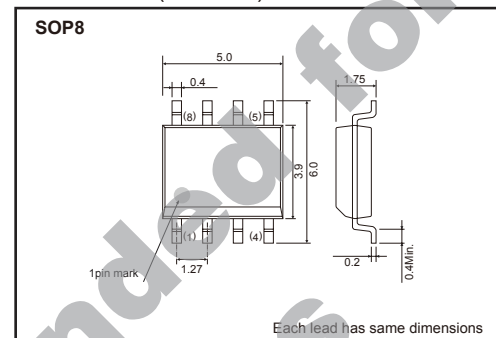
●Application

Power switching, DC / DC converter.

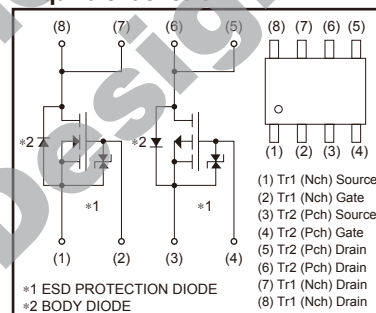
●Packaging specifications

Type	Package	Taping
	Code	TB
	Quantity (pcs)	2500
SP8M10FRA		○

●Dimensions (Unit : mm)



●Equivalent circuit



*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits		Unit	
		Nchannel	Pchannel		
Drain-source voltage	V _{DSS}	30	-30	V	
Gate-source voltage	V _{GSS}	±20	±20	V	
Drain current	Continuous	I _D	±7.0	±4.5	A
	Pulsed	I _{DP} *1	±28	±18	A
Source current (Body diode)	Continuous	I _S	1.6	-1.6	A
	Pulsed	I _{SP} *1	28	-18	A
Total power dissipation	P _D *2	2		W	
Channel temperature	T _{ch}	150		°C	
Storage temperature	T _{stg}	-55 to +150		°C	

*1 Pw≤10μs, Duty cycle≤1%

*2 MOUNTED ON A CERAMIC BOARD.

●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	R _{th (ch-a)} *	62.5	°C / W

*MOUNTED ON A CERAMIC BOARD.

Transistors

N-ch

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	–	–	±10	μA	V _{GS} =±20V, V _{DS} =0V
Drain-source breakdown voltage	V _{(BR) DSS}	30	–	–	V	I _D =1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	–	–	1	μA	V _{DS} =30V, V _{GS} =0V
Gate threshold voltage	V _{GS(th)}	1.0	–	2.5	V	V _{DS} =10V, I _D =1mA
Static drain-source on-state resistance	R _{DS(on)} *	–	17	25	mΩ	I _D =7.0A, V _{GS} =10V
		–	23	35		I _D =7.0A, V _{GS} =4.5V
		–	25	37		I _D =7.0A, V _{GS} =4V
Forward transfer admittance	Y _{fs} *	5.0	–	–	S	I _D =7.0A, V _{DS} =10V
Input capacitance	C _{iss}	–	600	–	pF	V _{DS} =10V
Output capacitance	C _{oss}	–	200	–	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	–	120	–	pF	f=1MHz
Turn-on delay time	t _{d(on)} *	–	8	–	ns	I _D =3.5A, V _{DD} ≐15V
Rise time	t _r *	–	10	–	ns	V _{GS} =10V
Turn-off delay time	t _{d(off)} *	–	37	–	ns	R _L =4.29Ω
Fall time	t _f *	–	11	–	ns	R _G =10Ω
Total gate charge	Q _g *	–	8.4	–	nC	V _{DD} ≐15V
Gate-source charge	Q _{gs} *	–	1.9	–	nC	V _{GS} =5V
Gate-drain charge	Q _{gd} *	–	3.3	–	nC	I _D =7.0A

*Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _{SD} *	–	–	1.2	V	I _S =6.4A, V _{GS} =0V

*Pulsed

Transistors

P-ch

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	–	–	±10	μA	V _{GS} = ±20V, V _{DS} =0V
Drain-source breakdown voltage	V _{(BR) DSS}	–30	–	–	V	I _D = –1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	–	–	–1	μA	V _{DS} = –30V, V _{GS} =0V
Gate threshold voltage	V _{GS(th)}	–1.0	–	–2.5	V	V _{DS} = –10V, I _D = –1mA
Static drain-source on-state resistance	R _{DS(on)} *	–	40	56	mΩ	I _D = –4.5A, V _{GS} = –10V
		–	57	80		I _D = –2.5A, V _{GS} = –4.5V
		–	65	90		I _D = –2.5A, V _{GS} = –4.0V
Forward transfer admittance	Y _{fs} *	3.5	–	–	S	I _D = –2.5A, V _{DS} = –10V
Input capacitance	C _{iss}	–	850	–	pF	V _{DS} = –10V
Output capacitance	C _{oss}	–	190	–	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	–	120	–	pF	f=1MHz
Turn-on delay time	t _{d(on)} *	–	10	–	ns	I _D = –2.5A, V _{DD} = –15V
Rise time	t _r *	–	25	–	ns	V _{GS} = –10V
Turn-off delay time	t _{d(off)} *	–	60	–	ns	R _L =6.0Ω
Fall time	t _f *	–	25	–	ns	R _G =10Ω
Total gate charge	Q _g *	–	8.5	–	nC	V _{DD} = –15V
Gate-source charge	Q _{gs} *	–	2.5	–	nC	V _{GS} = –5V
Gate-drain charge	Q _{gd} *	–	3.0	–	nC	I _D = –4.5A

*Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _{SD}	–	–	–1.2	V	I _S = –1.6A, V _{GS} =0V

Transistors

N-ch

●Electrical characteristic curves

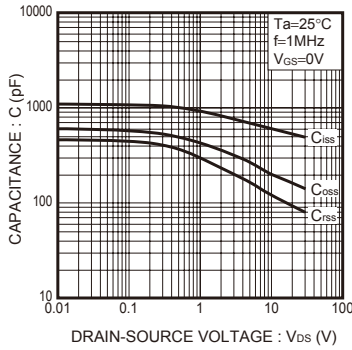


Fig.1 Typical Capacitance vs. Drain-Source Voltage

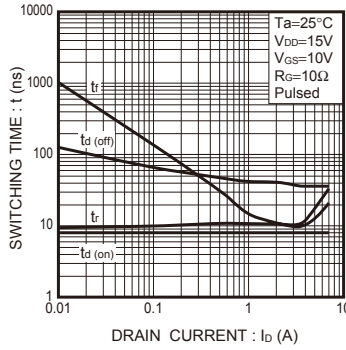


Fig.2 Switching Characteristics

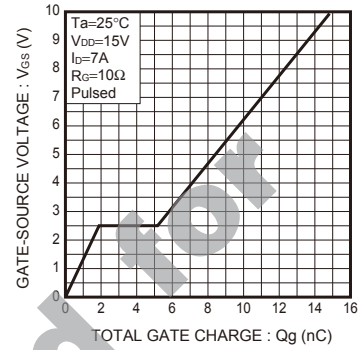


Fig.3 Dynamic Input Characteristics

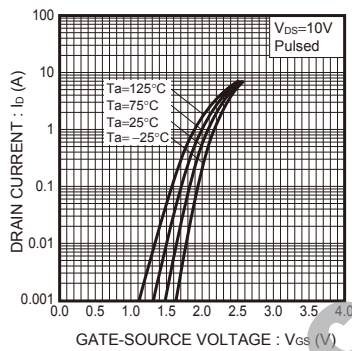


Fig.4 Typical Transfer Characteristics

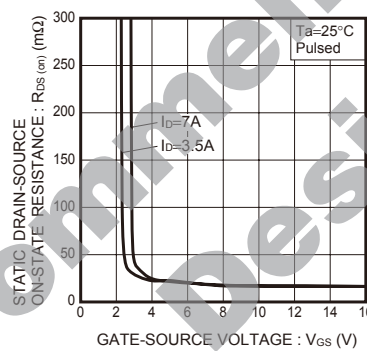


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

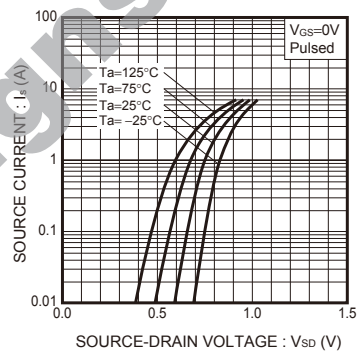


Fig.6 Source Current vs. Source-Drain Voltage

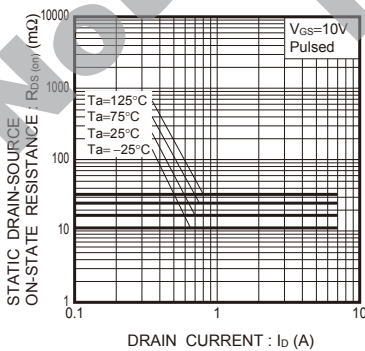


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

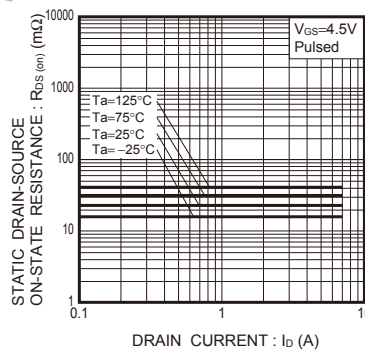


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

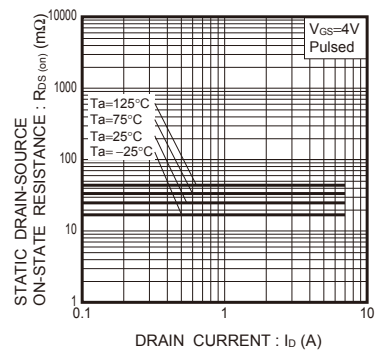


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

Transistors

P-ch

●Electrical characteristic curves

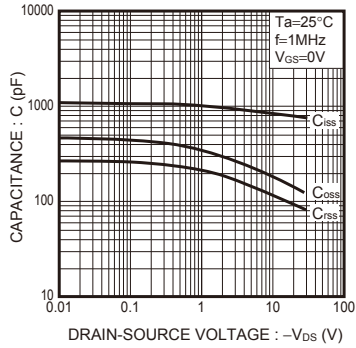


Fig.1 Typical Capacitance vs. Drain-Source Voltage

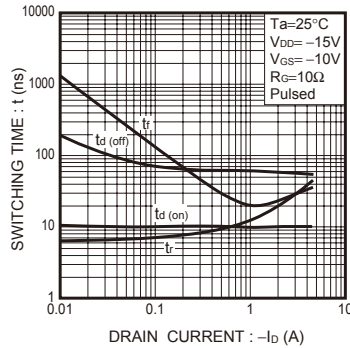


Fig.2 Switching Characteristics

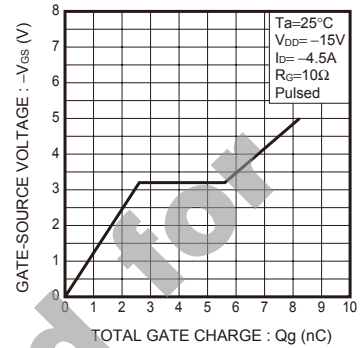


Fig.3 Dynamic Input Characteristics

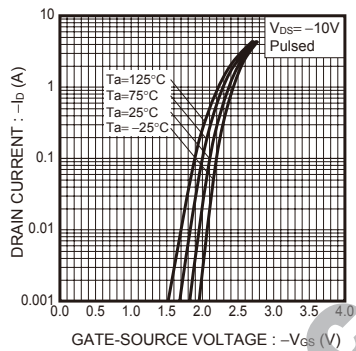


Fig.4 Typical Transfer Characteristics

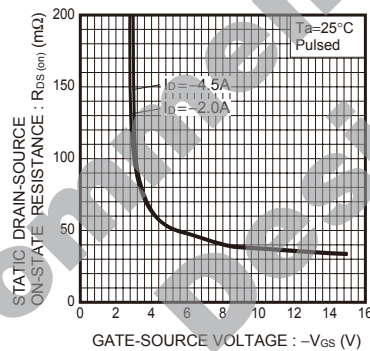


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

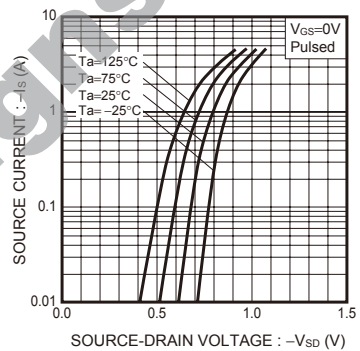


Fig.6 Source Current vs. Source-Drain Voltage

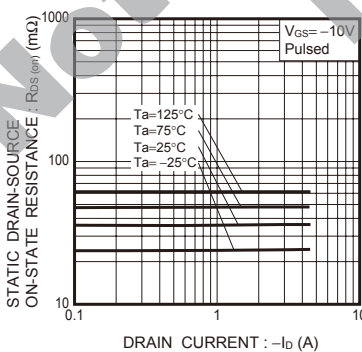


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

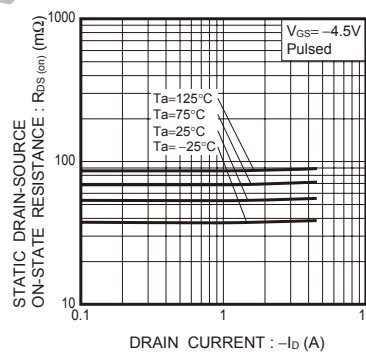


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

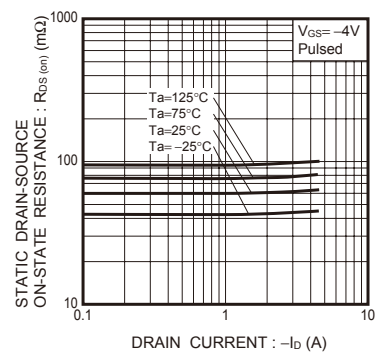


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
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